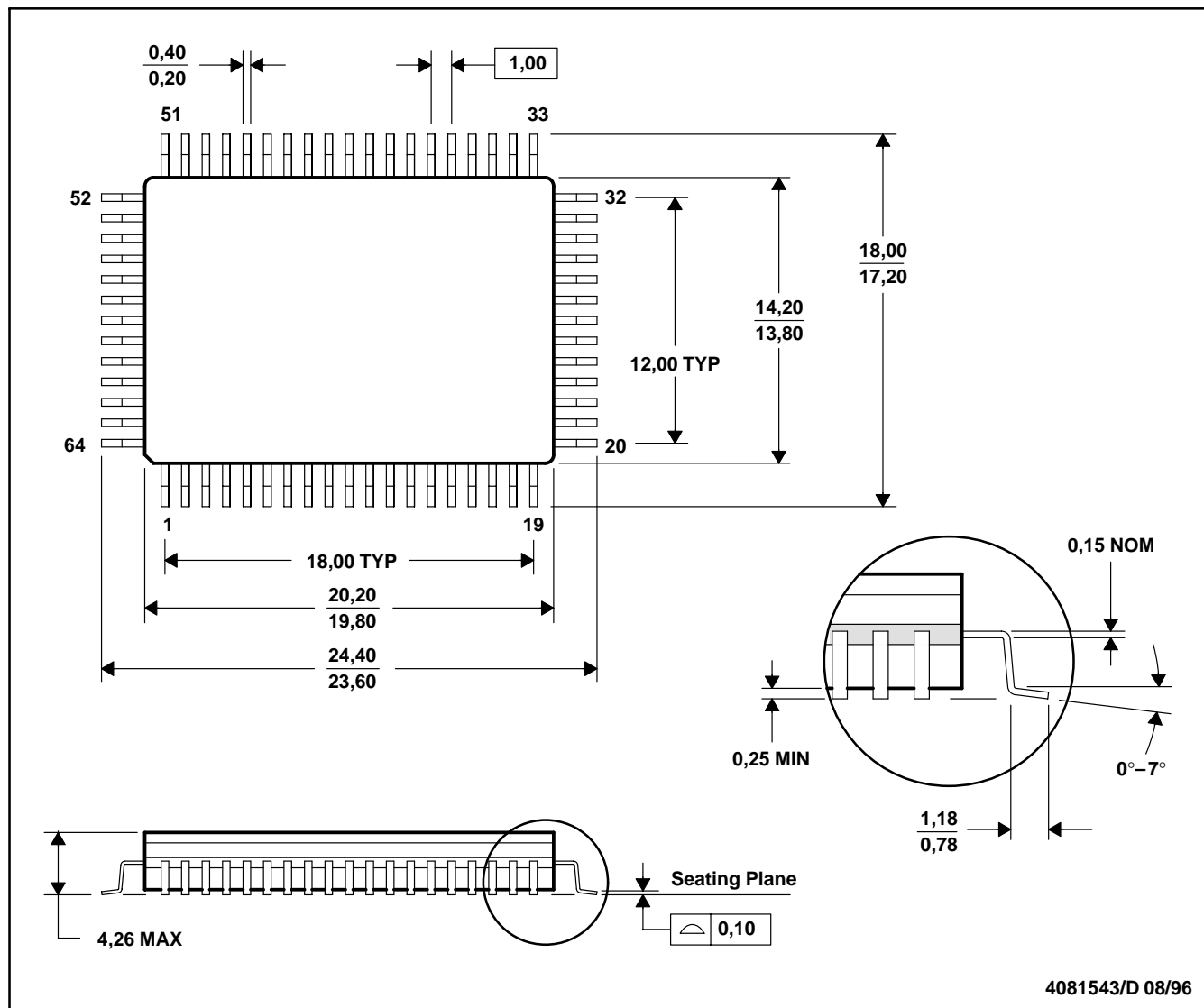


HBY (R-CQFP-G64)

CERAMIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.

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